



Material declaration form

| General Information | | | |
|---------------------|---------------------------|----------------|-------------------|
| IPC | 1752 | Version | 2 |
| Form type* | Distribute | | |
| Sectionals* | Material information | Subsectionals* | A-D |
| | Manufacturing information | | *: Required Field |

| Supplier Information | | | |
|----------------------------|--|-----------------------|-----------------------------------|
| Company name* | STMicroelectronics | Response Date* | 2025-03-09 |
| Contact name* | Refer to Supplier Comment section | | Refer to Supplier Comment section |
| Contact phone* | Refer to Supplier Comment section | Contact email* | Refer to Supplier Comment section |
| Authorized representative* | MDG CHAMPION | Representative title | MDGMaterial Declaration champion |
| Representative phone* | Refer to Supplier Comment section | Representative email* | Refer to Supplier Comment section |
| Supplier comment | Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html | | |

Uncertainty statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal statement

| Supplier acceptance* | true | Legal declaration* | Standard |
|---|------|--------------------|----------|
| Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. | | | |



| Product | | | | |
|-----------------|---------------|-----------------|--------------------|------------------|
| Mfr item number | Mfr item name | Version | Manufacturing site | date |
| STM32MP255CAK3 | E679*505XXXY | A | 9991 | 2025-03-09 |
| | Amount | Unit of measure | Unit type | ST ECOPACK grade |
| | 364 | mg | Each | ECOPACK® 2 |

| Manufacturing information | | | | |
|---------------------------|--|-------------------------|-------------|--|
| J-STD-020 MSL rating | Classification temperature | Number of reflow cycles | | |
| 3 | 260 | 3 | | |
| Bulk solder termination | Terminal plating | Terminal base alloy | Comment | |
| Not Applicable | Not Applicable | NAC | SACN305 | |
| Package designator | Package size | Number of instances | Shape | |
| BGA | 14x14 | 424 | Bulk solder | |
| Comment | Package : B0MP FC VFBGA 14X14 424B P0.5 DM01034187 | | | |

| QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015 | | Response |
|--|-------------|----------|
| 1 - Product(s) meets EU RoHS requirement without any exemptions | | true |
| 2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply) | | false |
| 3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s) | | false |
| 4 - Product(s) does not meet EU RoHS requirements and is not under exemptions | | false |
| Exemption Id. | Description | |
| , | | |

| QueryList : REACH-21st January 2025 | | | | Response |
|--|-------------------------|------------------------|-------------|----------------|
| QUERY | | | | Response |
| 1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH | | | | true |
| CategoryLevel_Name | CategoryLevel_Threshold | amount in product (mg) | Application | ppm in product |
| , | #N/A | | | |



| Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document | | | | | | Mfr Item Name | E679*505XXXY | | 364.1023 | | 5000000.0 | 1000000.0 | | | | |
|--|---------------------------------|--|-----------------|--------------------|--------------------|--|--------------|----------|-------------|---|---|--------------------------------|-------|----|--------|---------|
| Homogeneous material | Material group | Mass | Unit of measure | Level | Substance category | Substance | CAS | Exempt | Mass | Unit of measure | Concentration in homogeneous material (ppm) | Concentration in product (ppm) | | | | |
| Die or dies | M-011 Other inorganic materials | 10.000 | mg | supplier | die | Silicon(Si) | 7440-21-3 | | 9.329 | mg | 932860 | 25620.82 | | | | |
| | | | | supplier | metallisation | Aluminium(Al) | 7429-90-5 | | 0.005 | mg | 500 | 13.73 | | | | |
| | | | | supplier | metallisation | Arsenic(As) | 7440-38-2 | | 0.000 | mg | 4 | 0.11 | | | | |
| | | | | supplier | metallisation | Copper(Cu) | 7440-50-8 | | 0.498 | mg | 49763 | 1366.73 | | | | |
| | | | | supplier | metallisation | Cobalt(Co) | 7440-48-4 | | 0.000 | mg | 29 | 0.80 | | | | |
| | | | | supplier | metallisation | Silver(Ag) | 7440-22-4 | | 0.002 | mg | 196 | 5.38 | | | | |
| | | | | supplier | metallisation | Tantalum(Ta) | 7440-25-7 | | 0.005 | mg | 500 | 13.73 | | | | |
| | | | | supplier | metallisation | Tin(Sn) | 7440-31-5 | | 0.107 | mg | 10667 | 292.97 | | | | |
| | | | | supplier | metallisation | Titanium(Ti) | 7440-32-6 | | 0.001 | mg | 108 | 2.97 | | | | |
| | | | | supplier | metallisation | Tungsten(W) | 7440-33-7 | | 0.006 | mg | 550 | 15.11 | | | | |
| | | | | supplier | Passivation | Silicon Nitride (SiN) | 12033-89-5 | | 0.014 | mg | 1399 | 38.42 | | | | |
| | | | | supplier | passivation | Silicon Oxide | 7631-86-9 | | 0.034 | mg | 3424 | 94.04 | | | | |
| | | | | supplier | Solder Mask | Plastics PAK | Proprietary | | 3.141 | mg | 29826 | 8626.26 | | | | |
| | | | | Substrate (A32383) | Copper & Resin | 105.305 | mg | supplier | Solder Mask | Barium sulphate | 7727-43-7 | | 1.254 | mg | 11905 | 3443.16 |
| supplier | Solder Mask | Plastic EP | Proprietary | | | | | | 0.806 | mg | 7653 | 2213.40 | | | | |
| supplier | Solder Mask | Silicon dioxide | 7631-86-9 | | | | | | 0.640 | mg | 6074 | 1756.72 | | | | |
| supplier | Solder Mask | Additives, not to declare | Proprietary | | | | | | 0.288 | mg | 2733 | 790.44 | | | | |
| supplier | Solder Mask | Talc | 14807-96-6 | | | | | | 0.192 | mg | 1822 | 526.96 | | | | |
| supplier | Solder Mask | Pigment portion, not to declare | Proprietary | | | | | | 0.038 | mg | 364 | 105.28 | | | | |
| supplier | Solder Mask | Inorganic Ingredient, not to declare | Proprietary | | | | | | 0.038 | mg | 364 | 105.28 | | | | |
| supplier | PP | Thermosetting resin (including filler) | Proprietary | | | | | | 20.110 | mg | 190964 | 55230.50 | | | | |
| supplier | PP | Glass Cloth | 65997-17-3 | | | | | | 13.406 | mg | 127310 | 36820.52 | | | | |
| supplier | Cu foil | Copper | 7440-50-8 | | | | | | 7.307 | mg | 69388 | 20068.36 | | | | |
| supplier | Cu Plating | Copper | 7440-50-8 | | | | | | 58.086 | mg | 551597 | 159532.56 | | | | |
| Underfill (UA26) | Encapsulation Glue | 1.900 | mg | | | | | supplier | Underfill | p-(2,3-epoxypropoxy)-N, N-bis(2,3-epoxypropyl)a | 5026-74-4 | | 0.190 | mg | 100000 | 521.83 |
| | | | | | | | | supplier | Underfill | Bisphenol F type liquid epoxy resin | 9003-36-5 | | 0.190 | mg | 100000 | 521.83 |
| | | | | | | | | supplier | Underfill | Bisphenol A type liquid epoxy resin | 25068-38-6 | | 0.057 | mg | 30000 | 156.55 |
| | | | | supplier | Underfill | Amine type hardener | Proprietary | | 0.143 | mg | 75000 | 391.37 | | | | |
| | | | | supplier | Underfill | Carbon black | 1333-86-4 | | 0.010 | mg | 5000 | 26.09 | | | | |
| | | | | supplier | Underfill | Silicon dioxide | 60676-86-0 | | 1.235 | mg | 650000 | 3391.90 | | | | |
| | | | | supplier | Underfill | Additives | Proprietary | | 0.076 | mg | 40000 | 208.73 | | | | |
| Encapsulation (EME-G760-SW) | Molding Compound | 202.563 | mg | supplier | Molding compound | 2,2'-((3,3',5,5'-Tetramethyl-(1,1'-biphenyl)-4,4'-di | 85954-11-6 | | 16.205 | mg | 80000 | 44506.74 | | | | |
| | | | | supplier | Molding compound | Phenol Resin A | 9003-35-4 | | 8.103 | mg | 40000 | 22253.37 | | | | |
| | | | | supplier | Molding compound | Phenol Resin B | Proprietary | | 8.103 | mg | 40000 | 22253.37 | | | | |
| | | | | supplier | Molding compound | Silica(Amorphous) A | 60676-86-0 | | 121.538 | mg | 600000 | 333800.52 | | | | |
| | | | | supplier | Molding compound | Silica(Amorphous) B | 7631-86-9 | | 40.513 | mg | 200000 | 111266.84 | | | | |
| | | | | supplier | Molding compound | Metal Hydroxide | Proprietary | | 6.077 | mg | 30000 | 16690.03 | | | | |
| | | | | supplier | Molding compound | Carbon Black | 1333-86-4 | | 2.026 | mg | 10000 | 5563.34 | | | | |
| Solder balls (SACN305) | Other inorganic materials | 44.334 | mg | supplier | Solder Ball | Tin | 7440-31-5 | | 42.694 | mg | 963000 | 117258.03 | | | | |
| | | | | supplier | Solder Ball | Silver | 7440-22-4 | | 1.463 | mg | 33000 | 4018.19 | | | | |
| | | | | supplier | Solder Ball | Copper | 7440-50-8 | | 0.155 | mg | 3500 | 426.17 | | | | |
| | | | | supplier | Solder Ball | Nickel | 7440-02-0 | | 0.022 | mg | 500 | 60.88 | | | | |